

## Nelco N4000-13 EP™ Nelco N4000-13 EP™ SI®

### High-Speed Multifunctional Epoxy Laminate & Prepreg



Nelco N4000-13 EP™ is an enhanced epoxy resin system engineered for today's lead-free requirements where multiple solder reflow at temperatures approaching 260°C are required. N4000-13 EP provides enhanced thermal reliability without compromising the electrical and signal loss properties that have made the Nelco N4000-13 product family the industry standard for demanding high speed / low loss designs. The N4000-13 EP™ SI® is excellent for applications that require optimum signal integrity and precise impedance control, while maintaining high CAF\* resistance and thermal reliability.

### Key Features

#### Reliability through multiple lead-free excursions

- Engineered to withstand multiple solder reflows through a traditional SAC reflow profile (260°C)

#### Tg >210°C, outstanding thermal, electrical and signal loss properties

- Excellent thickness control for tight tolerance impedance applications
- Low Df and Dk allows for low signal distortion and faster signal propagation required by high frequency (1 - 10 GHz) and high reliability applications

#### CAF\* resistant

- The low Z-CTE and improved CAF resistance provide long-term reliability for both RF and digital applications
- Provides excellent CAF resistance even after multiple lead-free assembly exposures

#### Signal Integrity and Buried Capacitance™ options

- When used, SI glass provides enhanced electrical performance for even the most demanding applications
- Approved ZBC-2000® substrate available for thinner, more reliable assemblies and increased board densities

#### Proprietary advanced resin technology

- Industry standard material with well documented dielectric constant and loss tangent properties

#### High-Tg FR-4 processing

- Identical processing to the Nelco N4000-13. similar to traditional high Tg FR-4 materials
- 90 min press at 193°C and 275-350 psi

#### Available in a variety of constructions

- Vacuum laminated
- Available in a wide variety of constructions, copper weights and glass styles including standard copper, double treat and RTFOIL®.
- Meets UL 94V-0 and IPC-4101/29 specifications
- All Nelco materials are RoHS compliant.

### Applications

- Fine-Line Multilayers
- Backplanes
- Surface-Mount Multilayers
- BGA Multilayers
- MCM-Ls
- CSP Attachment
- Wireless Communication Infrastructure
- High Speed Services
- High Speed Storage Networks
- Internet Switching / Routing Systems

### Global Availability

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# Nelco N4000-13 EP™ and N4000-13 EP™ SI®

## High-Speed Multifunctional Epoxy Laminate & Prepreg

Mechanical Properties	-13 EP	-13 EP SI	U.S. Units	-13 EP	-13 EP SI	Metric	Test Method
Peel Strength - 1 oz. (35 micron) Cu							
After Solder Float	7.5	7.5	lb/inch	1.31	1.31	N/mm	IPC-TM-650.2.4.8
At Elevated Temperature	8.1	8.1	lb/inch	1.42	1.42	N/mm	IPC-TM-650.2.4.8.2a
After Exposure to Process Solutions	9.0	9.0	lb/inch	1.58	1.58	N/mm	IPC-TM-650.2.4.8
X/Y CTE [-40°C to +125°C]	10 - 14	9 - 13	ppm/°C	10 - 14	9 - 13	ppm/°C	IPC-TM-650.2.4.41
Z Axis CTE Alpha 1 [50°C to T <sub>g</sub> ]	65	65	ppm/°C	65	65	ppm/°C	IPC-TM-650.2.4.41
Z Axis CTE Alpha 2 [T <sub>g</sub> to 260°C]	275	275	ppm/°C	275	275	ppm/°C	IPC-TM-650.2.4.41
Z Axis Expansion [50°C to 260°C]	3.4	3.4	%	3.4	3.4	%	IPC-TM-650.2.4.41
Young's Modulus (X/Y)	4.2/3.3	TBD	psi x 10 <sup>6</sup>	28.5/22.4	TBD	GN/m <sup>2</sup>	ASTM D3039
Poisson's Ratios (X/Y)	0.13/0.11	TBD		0.13/0.11	TBD		ASTM D3039
Thermal Conductivity	0.350	0.294	W/mK	0.350	0.294	W/mK	ASTM E1461
Specific Heat	1.20	1.30	J/gK	1.20	1.30	J/gK	ASTM E1461
<b>Electrical Properties</b>							
Dielectric Constant (50% resin content)							
@ 1 GHz (RF Impedance)	3.7	3.4		3.7	3.4		IPC-TM-650.2.5.5.9
@ 2.5 GHz (Split Post Cavity)	3.7	3.2		3.7	3.2		
@ 10 GHz (Stripline)	3.6	3.2		3.6	3.2		IPC-TM-650.2.5.5.5
@ 10 GHz (Split Post Cavity)	3.7	3.3		3.7	3.3		
Dissipation Factor (50% resin content)							
@ 2.5 GHz (Split Post Cavity)	0.009	0.008		0.009	0.008		
@ 10 GHz (Stripline)	0.009	0.008		0.009	0.008		IPC-TM-650.2.5.5.5
@ 10 GHz (Split Post Cavity)	0.008	0.007		0.008	0.007		
Volume Resistivity							
C - 96/35/90	10 <sup>8</sup>	10 <sup>8</sup>	MΩ - cm	10 <sup>8</sup>	10 <sup>8</sup>	MΩ - cm	IPC-TM-650.2.5.17.1
E - 24/125	10 <sup>7</sup>	10 <sup>8</sup>	MΩ - cm	10 <sup>7</sup>	10 <sup>8</sup>	MΩ - cm	IPC-TM-650.2.5.17.1
Surface Resistivity							
C - 96/35/90	10 <sup>7</sup>	10 <sup>7</sup>	MΩ	10 <sup>7</sup>	10 <sup>7</sup>	MΩ	IPC-TM-650.2.5.17.1
E - 24/125	10 <sup>7</sup>	10 <sup>7</sup>	MΩ	10 <sup>7</sup>	10 <sup>7</sup>	MΩ	IPC-TM-650.2.5.17.1
Electric Strength	1200	1000	V/mil	4.7x10 <sup>4</sup>	3.9x10 <sup>4</sup>	V/mm	IPC-TM-650.2.5.6.2
Dielectric Breakdown	>50	>50	kV	>50	>50	kV	IPC-TM-650.2.5.6
Arc Resistance	123	123	seconds	123	123	seconds	IPC-TM-650.2.5.1
<b>Thermal Properties</b>							
Glass Transition Temperature (T <sub>g</sub> )							
DSC (°C)	210	210	°C	210	210	°C	IPC-TM-650.2.4.25c
TMA (°C)	200	200	°C	200	200	°C	IPC-TM-650.2.4.24c
DMA (°C) (Tan δ Peak)	240	240	°C	240	240	°C	IPC-TM-650.2.4.24.3
Degradation Temp (TGA) (5% wt. loss)	365	365	°C	365	365	°C	IPC-TM-650.2.4.24.6
Pressure Cooker-60 min then solder dip							IPC-TM-650.2.6.16
@288°C until failure (max 10 min.)	Pass	Pass		Pass	Pass		(modified)
T <sub>260</sub>	30+	30+	minutes	30+	30+	minutes	IPC-TM-650.2.4.24.1
T <sub>288</sub>	10+	10+	minutes	10+	10+	minutes	IPC-TM-650.2.4.24.1
<b>Chemical/Physical Properties</b>							
Moisture Absorption	0.1	0.1	wt. %	0.1	0.1	wt. %	IPC-TM-650.2.6.2.1
Methylene Chloride Resistance	0.7	0.7	% wt. chg.	0.7	0.7	% wt. chg.	IPC-TM-650.2.3.4.3
Density [50% resin content]	1.77	1.64	g/cm <sup>3</sup>	1.77	1.64	g/cm <sup>3</sup>	Internal Method

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All test data provided are typical values and not intended to be specification values. For review of critical specification tolerances, please contact a Nelco representative directly. Nelco reserves the right to change these typical values as a natural process of refining our testing equipment and techniques.

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\*CAF resistance has been established to greater than 500 hours using a specific OEM coupon design and test procedure. For details on this or other CAF tests, please visit [www.parelelectro.com](http://www.parelelectro.com).

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